L	Hits	Search Text	DB	Time stamp
Number				
1	0	laser adj2 chip\$1 and cool\$3 adj2 element	USPAT;	2004/07/27
		and chip adj2 mount\$3 adj2 area and	EPO; JPO;	15:54
		(divid\$3 or cut\$3)	DERWENT	
2	15		USPAT;	2004/07/27
		and solder\$3 and (divid\$3 or cut\$3)	EPO; JPO; DERWENT	16:12
3	57	laser adj2 chip\$1 and heat adj2 sink and	USPAT;	2004/07/27
		ceramic and (divid\$3 or cut\$3)	EPO; JPO;	16:14
			DERWENT	
4	53	(laser adj2 chip\$1 and heat adj2 sink and	USPAT;	2004/07/27
		ceramic and (divid\$3 or cut\$3)) not	EPO; JPO;	16:13
		(laser adj2 chip\$1 and cool\$3 adj2	DERWENT	
		element and solder\$3 and (divid\$3 or		
		cut\$3))		
5	0	laser adj2 chip\$1 and heat adj2 sink and	USPAT;	2004/07/27
		ceramic and (divid\$3 or cut\$3) and chip	EPO; JPO;	16:15
		adj2 mount\$3 adj2 area	DERWENT	
6	0		USPAT;	2004/07/27
		ceramic and (divid\$3 or cut\$3) and chip	EPO; JPO;	16:15
-	_	near5 mount\$3 adj2 area	DERWENT	
7	1	laser adj2 chip\$1 and heat adj2 sink and	USPAT;	2004/07/27
		ceramic and (divid\$3 or cut\$3) and chip	EPO; JPO;	16:23
	_	near5 mount\$3 near5 area	DERWENT	2004/07/27
8	5		USPAT;	2004/07/27
		(divid\$3 or cut\$3) and (plate or carrier)	EPO; JPO; DERWENT	16:25
9	_	and chip near5 mount\$3 near5 area		2004/07/27
"	3	laser adj2 chip\$1 and ((heat adj2 sink) or cooling) and (divid\$3 or cut\$3) and	USPAT; EPO; JPO;	16:25
		(plate or carrier) and chip near5 mount\$3	DERWENT	10.23
		near5 area	DEKMENI	
	L	Hears area	L	